

## PRODUCT DATA SHEET

# TACFlux® 26S

### Features

- Halogen-free – no intentionally added (NIA) halogens
- Suitable for Pb-free alloys
- Compatible with underfills
- Dipping with minimal bridging
- Designed for rework applications
- Low residue
- Bubble-free (airless) packaging

### Introduction

**TACFlux® 26S** is a NIA halogen-free, no-clean rework flux, which is designed to leave a completely benign, clear residue. The reduction in residue optimizes underfill adhesion and decreases possible outgassing during underfill cure.

### Properties

Property	Value	Test Method
Flux Classification:	RELO	J-STD-004 (IPC-TM-650: 2.3.32 and 2.3.33)
Color:	Light Yellow	Visual
Typical Viscosity:	13 kcps	Brookfield HB DVII+-CP (20rpm)
SIR (Ohms):	Pass (>10 <sup>3</sup> after 7 days @ 85°C & 85% RH)	J-STD-004 (IPC-TM-650: 2.6.3.3 IPC-B-24)
Typical Acid Value:	39mg KOH/g	Titration
Shelf Life:	6 months @ 0 to 30°C	Viscosity change/microscope examination
Typical Post Reflow Residual Weight:	<10%	TGA

All information is for reference only. Not to be used as incoming product specifications.

### Application

**TACFlux® 26S** is intended to be used in a nitrogen reflow environment of 100ppm oxygen or less. Some applications can utilize this material in an air environment, although best results will be obtained in an inert atmosphere. **TACFlux® 26S** can be used on many surface finishes including immersion Ag, Cu-OSP, AuNi, and AuPdNi, and is compatible with all standard flip-chip solders.



### Compatibility

The compatibility of flip-chip flux residues with epoxy-based capillary underfills is determined by measuring the shear strength of the interface between the post-reflow flux and the cured underfill. The best results for **TACFlux® 26S** have been observed with both amine- and acid anhydride-based capillary underfill chemistries.

### Cleaning

**TACFlux® 26S** is designed for no-clean applications. If necessary, the flux can be removed by using a commercially available flux cleaner. Please contact an Indium Corporation Technical Service Engineer for recommendations of cleaners to suit your process needs.

### Storage

**TACFlux® 26S** syringes and cartridges should be stored tip down at 0° to 30°C for maximum shelf life. **TACFlux® 26S** should be allowed to reach ambient temperature before use.

### Packaging

**TACFlux® 26S** is most commonly available in 10 and 30cc syringes. Other packaging can be provided to meet specific requirements.

OVER→

Form No. 98999 (A4) R2

[www.indium.com](http://www.indium.com)

[askus@indium.com](mailto:askus@indium.com)

ASIA: Singapore, Cheongju, Malaysia: +65 6268 8678  
 CHINA: Suzhou, Shenzhen: +86 (0)512 628 34900  
 EUROPE: Milton Keynes, Torino: +44 (0) 1908 580400  
 USA: Utica, Clinton, Chicago, Rome: +1 315 853 4900



ISO 9001  
REGISTERED

### Technical Support

Indium Corporation sets the industry standard in providing rapid response, on-site technical support for our customers worldwide. Indium Corporation's team of Technical Support Engineers can provide expertise in all aspects of materials science and semiconductor packaging process applications.

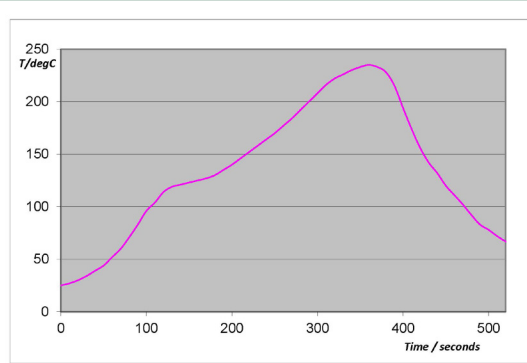
### Safety Data Sheets

The SDS for this product can be found online at <http://www.indium.com/sds>

### Reflow

#### Recommended Profile:

Reflow Profile: SAC305



A short preheat (150°-160 °C) for less than 45 seconds may be used to reduce voiding. The profile should ideally be a linear ramp at 2-3 °C/second up to 20-30 °C above solidus temperature, with a slow cool down afterwards of -0.5 to -0.2 °C, and a minimum time above liquidus of 60 seconds.

This product data sheet is provided for general information only. It is not intended, and shall not be construed, to warrant or guarantee the performance of the products described which are sold subject exclusively to written warranties and limitations thereon included in product packaging and invoices. All Indium Corporation's products and solutions are designed to be commercially available unless specifically stated otherwise.

[www.indium.com](http://www.indium.com)

[askus@indium.com](mailto:askus@indium.com)

ASIA: Singapore, Cheongju, Malaysia: +65 6268 8678

CHINA: Suzhou, Shenzhen: +86 (0)512 628 34900

EUROPE: Milton Keynes, Torino: +44 (0) 1908 580400

USA: Utica, Clinton, Chicago, Rome: +1 315 853 4900



ISO 9001  
REGISTERED